

2.0x1.25mm SMD CHIP LED LAMP

Part Number: APHBM2012SURKCGKC

Hyper Red Green

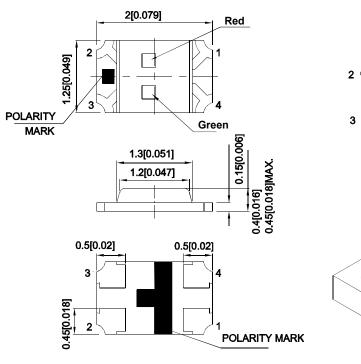
Features

- 2.0mmx1.25mm SMD LED, 0.45mm max. thickness.
- Bi -color, low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

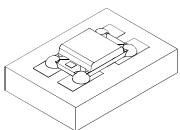
Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAG7623 **APPROVED: Wynec**

REV NO: V.12A CHECKED: Allen Liu

DATE: MAY/18/2016 DRAWN: M.Liu

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APHBM2012SURKCGKC	Hyper Red (AlGaInP)	- Water Clear	120	250	- 120°
			*40	*80	
	Green (AlGaInP)		20	50	
			*20	*50	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity / luminous Flux: +/-15%.
 Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Hyper Red Green	645 574		nm	IF=20mA	
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	I==20mA	
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	IF=20mA	
С	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	IF=20mA	
lR	Reverse Current	Hyper Red Green		10 10	uA	V _R = 5V	

Notes:

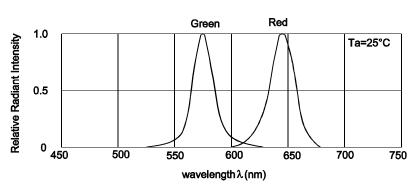
- Wavelength: +/-1nm.
 Forward Voltage: +/-0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Units		
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	185	150	mA		
Reverse Voltage		V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

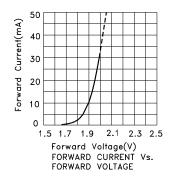
- Notes:
 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

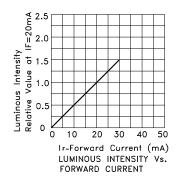
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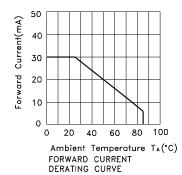


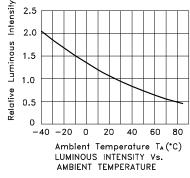
Relative Intensity Vs. Wavelength

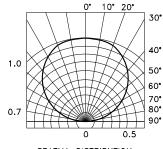
APHBM2012SURKCGKC Hyper Red









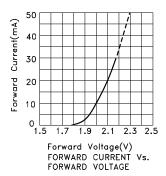


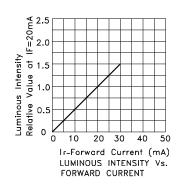
SPATIAL DISTRIBUTION

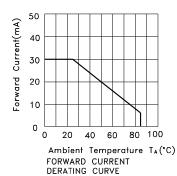
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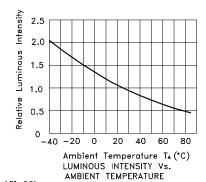
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Green



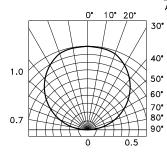






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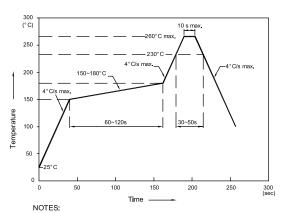
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

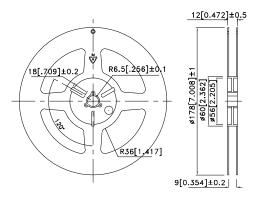
Reflow Soldering Profile For Lead-free SMT Process.



- 1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

Reel Dimension

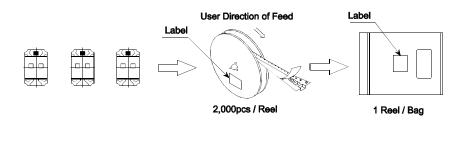


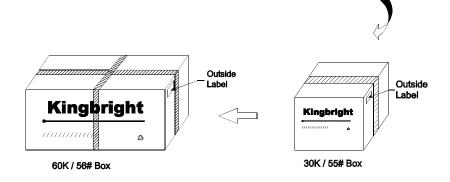
Tape Dimensions (Units: mm)

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PACKING & LABEL SPECIFICATIONS

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